

REVISIONS																			
LTR	DESCRIPTION										DATE (YR-MO-DA)					APPROVED			
B	Inactivate for new design device 01CX. Add vendor CAGE 27014 to case outline 2. Convert to military drawing format. Editorial changes throughout.										1 JAN. 88					M. A. Frye			
<p><i><u>This page has been electronically altered and does not match the original.</u></i></p>																			
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PMIC N/A				PREPARED BY James E Nicklaus						DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444									
<p>MILITARY DRAWING</p> <p>THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE</p> <p>AMSC N/A</p>				CHECKED BY D A Di Cenzo															
				APPROVED BY Michael A. Frye															
				DRAWING APPROVAL DATE 24 Sep 1984															
				REV B															
				TITLE: MICROCIRCUITS, DIGITAL, HEX INVERTING, SCHMITT TRIGGER, HCMOS, MONOLITHIC SILICON															
						SIZE A		CAGE CODE 14933		84091									
						SHEET		1		OF		10							

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.
DESC FORM 193
MAY 86

5962-E668

1. SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:

84091	01	A	X
_____	_____	_____	_____
Drawing number	Device type (1.2.1)	Case outline (1.2.2)	Lead finish per MIL-M-38510

1.2.1 Device type. The device type shall identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	54HC14	Hex inverting Schmitt trigger

1.2.2 Case outlines. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

<u>Outline letter</u>	<u>Case outline</u>
A	F-1 (14-lead, 1/4" x 1/4"), flat package
B	F-3 (14-lead, 3/16" x 1/4"), flat package
C	D-1 (14-lead, 1/4" x 3/4"), dual-in-line package
D	F-2 (14-lead, 1/4" x 3/8"), flat package
2	C-2 (20-terminal, .358" x .358") square chip carrier package

1.3 Absolute maximum ratings. 1/

Supply voltage range - - - - -	-0.5 V dc to +7.0 V dc
DC input voltage- - - - -	-0.5 V dc to V_{CC} +0.5 V dc
DC output voltage - - - - -	-0.5 V dc to V_{CC} +0.5 V dc
Clamp diode current - - - - -	+20 mA
DC output current (per pin)- - - - -	+25 mA
DC V_{CC} or GND current (per pin) - - - - -	+50 mA
Storage temperature range - - - - -	-65°C to +150°C
Maximum power dissipation, (P_D) - - - - -	500 mW 2/
Lead temperature (soldering, 10 seconds) - - - - -	+260°C
Thermal resistance, junction-to-case (Θ_{JC}):	
Cases A, B, C, D, and 2- - - - -	(See MIL-M-38510, appendix C)
Junction temperature (T_J) - - - - -	+175°C

1.4 Recommended operating conditions.

Supply voltage range (V_{CC}) - - - - -	+2.0 V dc minimum to +6.0 V dc maximum
Case operating temperature range (T_C) - - - - -	-55°C to +125°C
Input rise or fall time:	
V_{CC} = 2.0 V- - - - -	0 to 1000 ns
V_{CC} = 4.5 V- - - - -	0 to 500 ns
V_{CC} = 6.0 V- - - - -	0 to 400 ns

1/ Unless otherwise specified, all voltages are referenced to ground.

2/ For T_C = +100°C to +125°C, derate linearly at 12 mW/°C.

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2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARDS

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standards required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections and logic diagram. The terminal connections and logic diagram shall be as specified on figure 1.

3.2.2 Truth table. The truth table shall be as specified on figure 2.

3.2.3 Switching waveforms. The switching waveforms shall be as specified on figure 3.

3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.

3.4 Marking. Marking shall be in accordance with MIL-STD-833 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.3 herein.

3.5 Certification of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.3. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C unless otherwise specified 1/		Group A subgroups	Limits		Unit
					Min	Max	
High-level output voltage	V _{OH}	V _{IN} = V _{IH} or V _{IL} I _O ≤ 20 μA	V _{CC} = 2.0 V	1, 2, 3	1.9		V
			V _{CC} = 4.5 V		4.4		
			V _{CC} = 6.0 V		5.9		
		I _O ≤ 4.0 mA	V _{CC} = 4.5 V		3.7		
		I _O ≤ 5.2 mA	V _{CC} = 6.0 V		5.2		
Low-level output voltage	V _{OL}	V _{IN} = V _{IH} or V _{IL} I _O ≤ 20 μA	V _{CC} = 2.0 V	1, 2, 3		0.1	V
			V _{CC} = 4.5 V			0.1	
			V _{CC} = 6.0 V			0.1	
		I _O ≤ 4.0 mA	V _{CC} = 4.5 V			0.4	
		I _O ≤ 5.2 mA	V _{CC} = 6.0 V			0.4	
Hysteresis voltage 2/	V _H		V _{CC} = 2.0 V	1, 2, 3	0.2	1.2	V
			V _{CC} = 4.5 V		0.4	2.10	
			V _{CC} = 6.0 V		0.50	2.50	
Positive-going threshold voltage 2/	V _T		V _{CC} = 2.0 V	1, 2, 3	0.70	1.5	V
			V _{CC} = 4.5 V		1.55	3.15	
			V _{CC} = 6.0 V		2.10	4.2	
Negative-going threshold voltage 2/	V _{T-}		V _{CC} = 2.0 V	1, 2, 3	0.3	1.00	V
			V _{CC} = 4.5 V		0.9	2.45	
			V _{CC} = 6.0 V		1.20	3.20	
Input capacitance	C _{IN}	V _{IN} = 0 V T _C = +25°C See 4.3.1c		4		10	pF
Quiescent current	I _{CC}	V _{CC} = 6.0 V V _{IN} = V _{CC} or GND		1, 2, 3		40	μA
Input leakage current	I _{IN}	V _{CC} = 6.0 V V _{IN} = V _{CC} or GND		1, 2, 3		±1	μA

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C unless otherwise specified <u>1/</u>		Group A subgroups	Limits		Unit
					Min	Max	
Functional tests		See 4.3.1d.		7			
Propagation delay time, high to low, low to high <u>3/</u>	t _{PHL} t _{PLH}	T _C = +25°C, C _L = 50 pF ±10% See figure 3	V _{CC} = 2.0 V	9		140	ns
			V _{CC} = 4.5 V			28	
			V _{CC} = 6.0 V			24	
		T _C = -55°C, +125°C, C _L = 50 pF ±10% See figure 3	V _{CC} = 2.0 V	10, 11		210	ns
			V _{CC} = 4.5 V			42	
			V _{CC} = 6.0 V			36	
Transition time high to low, low to high <u>4/</u>	t _{THL} t _{TLH}	T _C = +25°C, C _L = 50 pF ±10%, See figure 3	V _{CC} = 2.0 V	9		75	ns
			V _{CC} = 4.5 V			15	
			V _{CC} = 6.0 V			13	
		T _C = -55°C, +125°C, C _L = 50 pF ±10%, See figure 3	V _{CC} = 2.0 V	10, 11		110	ns
			V _{CC} = 4.5 V			22	
			V _{CC} = 6.0 V			19	

1/ For a power supply of 5 V ±10% the worst case output voltages (V_{OH} and V_{OL}) occur for HC at 4.5 V. Thus, the 4.5 V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC} = 5.5 V and 4.5 V respectively. (The V_{IH} value at 5.5 V is 3.85 V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage, so the 6.0 V values should be used. Power dissipation capacitance (C_{PD}), typically 27 pF, determines the no load dynamic power consumption, P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}, and the no load dynamic current consumption, I_S = C_{PD} V_{CC} f + I_{CC}.

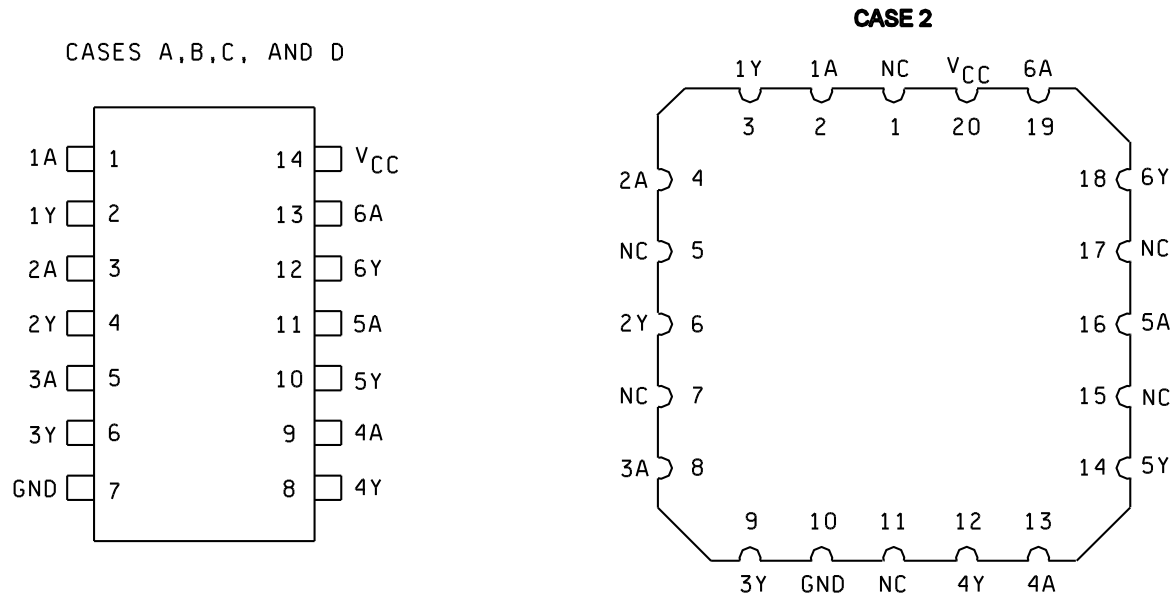
2/ Test not required if applied as a forcing function for V_{OH} or V_{OL}.

3/ Propagation delay times, when V_{CC} = 2.0 V and 6.0 V shall be guaranteed, if not tested, to the specified parameters.

4/ Transition times, (t_{TLH}, t_{THL}), if not tested, shall be guaranteed to the specified limits.

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DEVICE TYPE 01



LOGIC DIAGRAM

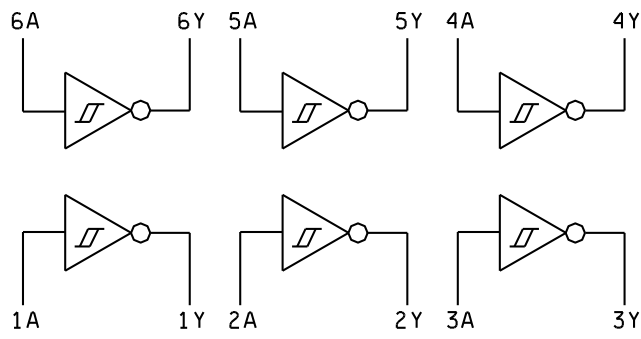


FIGURE 1. Terminal connections and logic diagram.

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Device type 01

Truth Table Each Gate	
Input	Output
A	Y
L	H
H	L

Positive logic $Y = \bar{A}$

FIGURE 2. Truth table.

DEVICE TYPE 01

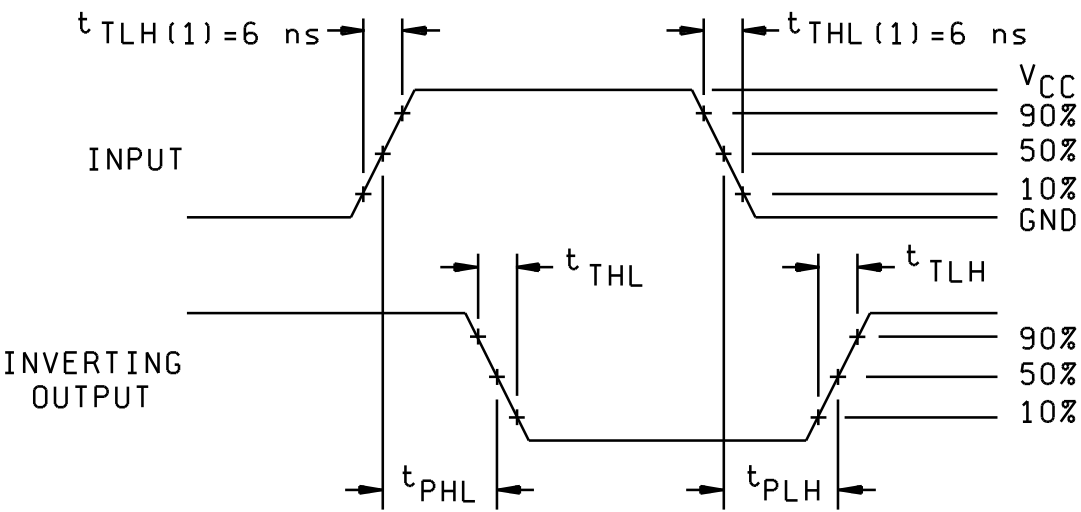


FIGURE 3. Switching waveforms.

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3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).

3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test (method 1015 of MIL-STD-883).

(1) Test condition A, B, C, D using the circuit submitted with the certificate of compliance (see 3.5 herein).

(2) $T_A = +125^{\circ}\text{C}$, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 5, 6, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.

c. Subgroup 4 (C_{IN} measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance.

d. Subgroup 7 tests sufficiently to verify the truth table.

4.3.2 Groups C and D inspections.

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test (method 1005 of MIL-STD-883) conditions:

(1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).

(2) $T_A = +125^{\circ}\text{C}$, minimum.

(3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*, 2, 9
Group A test requirements (method 5005)	1, 2, 3, 4, 7, 9, 10, 11**
Group C and D end-point electrical parameters (method 5005)	1, 2, 3

* PDA applies to subgroup 1.

** Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 Replaceability. Replaceability is determined as follows:

a. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

b. When a QPL source is established, the part numbered device specified in this drawing will be replaced by the microcircuit identified as part number M38510/65702- - -.

6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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6.4 Approved sources of supply. Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1/</u>	Replacement military specification part number
8409101AX <u>2/</u>			
8409101BX	01295	SNJ54HC14WA	M38510/65702BBX
8409101CX <u>3/</u>	04713	54HC14/BCAJC	M38510/65702BCX
	01295	SNJ54HC14J	
	27014	MM54HC14J/883B	
	18714	CD54HC14F/3A	
8409101DX	01295	SNJ54HC14W	M38510/65702BDX
84091012X	01295	SNJ54HC14FK	M38510/65702B2X
	27014	MM54HC14E/883	
	04713	54HC14M/B2CJC	

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

2/ Not supplied by an approved source.

3/ Inactive for new design. Use MIL-M-38510/65702BCX.

Vendor CAGE
number

Vendor name
and address

01295

Texas Instruments, Inc.
P.O. Box 6448
Midland, TX 79701

04713

Motorola, Inc.
7402 S. Price Road
Tempe, AZ 85283

18714

RCA Solid State Division
Route 202
Somerville, NJ 08876

27014

National Semiconductor
P.O. Box 58090
Santa Clara, Ca 95052-8090

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